TOSHIBA SG800EX25

TENTATIVE

TOSHIBA GATE TURN-OFF THYRISTOR

SG800EX25

INVERTER APPLICATION

Repetitive Peak Off-State Voltage : $V_{DRM} = 2500V$

(Note 1)

Repetitive Peak Reverse Voltage $: V_{RRM} = 1250V$

R.M.S On-State Current $: I_{T(RMS)} = 400A$

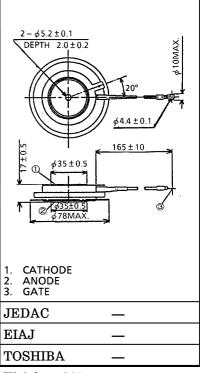
Peak Turn-Off Current $: I_{TGOM} = 800A$

Critical Rate of Rise of On-State Current : di/dt=100A/ μ s

Critical Rate of Rise of Off-State Voltage: dv/dt=350V/\mu s

MAXIMUM RATINGS

CHARACTERISTIC	SYMBOL	RATING	UNIT	
Repetitive Peak Off-State Voltage (Note 1)	$v_{ m DRM}$	2500	V	
Repetitive Peak Reverse Voltage	v_{RRM}	1250	V	
Peak Turn-Off Current (Note 2)	I_{TGQM}	800	Α	
R.M.S On-State Current (Note 3)	I _T (RMS)	400	Α	
Peak One Cycle Surge On-State Current (Non Repetitive, 10ms-	Imazz	5000 (50Hz)	A	
Width Half Sine Waveform)	^I TSM	5500 (60Hz)		
Critical Rate of Rise of On-State Current (Note 4)	di / dt	100	A/μs	
Peak Forward Gate Current	I_{FGM}	10	A	
Average Gate Forward Power Dissipation	P _{FG (AV)}	4	w	
R.M.S Gate Current (Note 5)	I _G (RMS)	35	Α	
Peak Reverse Gate Voltage (At Static)	v_{RGM}	15	V	
Operation Junction Temperature Range	Tj	-40~115	$^{\circ}\mathrm{C}$	
Storage Temperature Range	$\mathrm{T}_{\mathrm{stg}}$	-40~115	$^{\circ}\mathrm{C}$	
Mounting Force	_	11.8 ± 1.2	kN	



Unit in mm

Weight: 260g

- (Note 1) $R_{GK} = 20\Omega$
- $V_D = 1250V$, $V_{DM} \le 2/3V_{DRM}$, $C_S \ge 2\mu F$, $di_{QQ}/dt \ge 30A/\mu s$, $V_{DSP} \le 600V$, (Note 2) $L_{\mathbf{S}} \leq 0.2 \mu \mathbf{H}$
- (Note 3) 50Hz Half Sine Waveform
- (Note 4) $V_D \le 1250V$, $I_{TM} \le 800A$, $I_G \ge 5A$ ($t_r \le 1\mu s$), $f \le 50Hz$, $C_S \le 2\mu F$, $R_S \ge 20\Omega$, $25^{\circ}\text{C} \leq \text{T}_{i} \leq 115^{\circ}\text{C}$
- (Note 5) Ambient Temperature of gate and cathode lead=90°C

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ELECTRICAL CARACTERISTICS

CHARACTERISTICS	SYMBOL	TEST CONDITION		MIN.	TYP.	MAX.	UNIT
Repetitive Peak Off-State Current	$I_{ m DRM}$	$V_{DRM} = 2500V, V_{GK} = -2V$ $T_{j} = 115^{\circ}C$		_	_	50	mA
Repetitive Peak Reverse Current	I _{RRM}	$\overline{V_{RRM}} = 1250V$ $T_j = 115$ °C		_	1	50	mA
Repetitive Peak Reverse Gate Current	I_{RGM}	V_{RGM} =15V T_j =115°C		_	_	10	mA
Peak On-State Voltage	V_{TM}	$I_{TM} = 600A, T_j = 25^{\circ}C$		_	_	2.5	V
Gate Trigger Voltage	v_{GT}		$T_j = -40^{\circ}C$	_		_	V
		$V_D = 24V$	$T_j = 25$ °C	_	0.65	2.0	V
Gate Trigger Current	I_{GT}	$R_{\rm L} = 0.1\Omega$	$T_j = -40^{\circ}C$	_	400	_	mA
		"	$T_j = 25$ °C	-	120	350	mA
Turn-On Delay Time	^t d	$V_D = 1250V, I_{TM} = 800A$ di / dt = 100A / μs		_	_	4.0	μs
Turn-On Time	t _{gt}	$I_{GM}=5A \ (t_r=1\mu s) \ T_j=25^{\circ}C, \ non-snubber$		_	_	10	μs
Critical Rate of Rise of Off- State Voltage	dv/dt	$V_{ m DRM} = 2/3V_{ m DRM}$ $T_{ m j} = 115^{\circ}{ m C}, \ V_{ m GK} = -4V$ Exponential Rise		350		_	V/μs
Storage Time	$t_{\rm S}$	$I_{TGQ} = 600A$		_	_	15	μs
Gate Turn-Off Time	t_{gq}	$V_{DM} = 2/3V_{DRM}$, $T_j = 115$ °C		_	_	18	μs
Tail Time	t _{tail}	$({ m V_D}{=}1250{ m V}),~{ m C_S}{=}2\mu{ m F} \ { m di_{GQ}}/{ m dt}{=}30{ m A}/\mu{ m s}$		_	150	_	μs
Gate Turn-Off Current	I_{GQ}	Off squeeze current \geq 300mA		_	180	_	A
Thermal Resistance	R _{th (j-f)}	Junction to fin		_		0.04	°C/W